

FEE TRANSMITTAL

Electronic Version

Stylesheet Version v08.0

**Title of
Invention**METHOD OF SOLDERING SEMICONDUCTOR PART AND MOUNTED
STRUCTURE OF SEMICONDUCTOR PART

Application Number :

Date :

First Named Applicant: Akihiro Mano

Attorney Docket Number: 22040-00034-US1

Art Unit: N/A

Examiner : Not Yet Assigned

TOTAL FEE AUTHORIZED \$ 425

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as small entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	2001	385	385
Subtotal For Basic Filing Fees: \$ 385			

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 4	0	2202	9	0
Independent Claims : 2	0	2201	43	0
Subtotal For Extra Claims Fees: \$ 0				

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee		1	8021	40	40
Subtotal For Additional Fees: \$40					

AUTHORIZED BILLING INFORMATION

Deposit account number: 220185

Access Code ****

Deposit name: Connolly Bove Lodge & Hutz LLP

Deposit authorized name: Larry J. Hume

Signature: /ljh/

Date (YYYYMMDD):

2004-08-10